



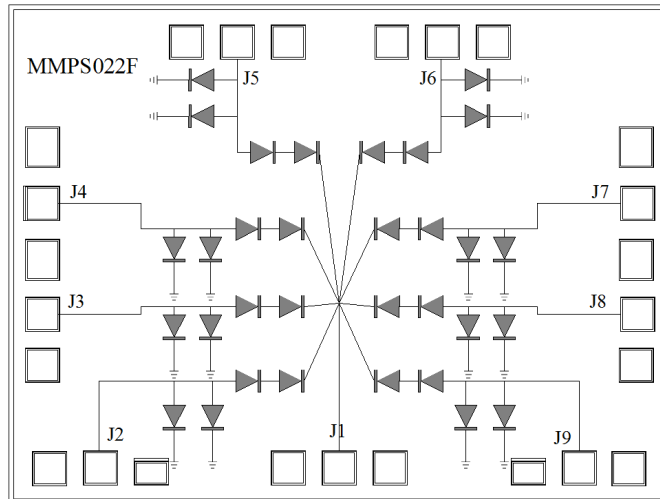
Features

- PIN Diode SP8T Reflective design
- Frequency:0.1-26.5GHz
- Isolation: 40dB Typical
- Insertion Loss: 1.3dB Typical
- Control Voltage:+5/-5V
- Switching Speed:10ns
- Die Size: 1.95 x 1.47 x 0.1 mm

Typical Applications

- Voltage control
- Fast Switching Speed
- Low Insertion Loss and High Isolation
- Customization available upon request

Functional Block Diagram



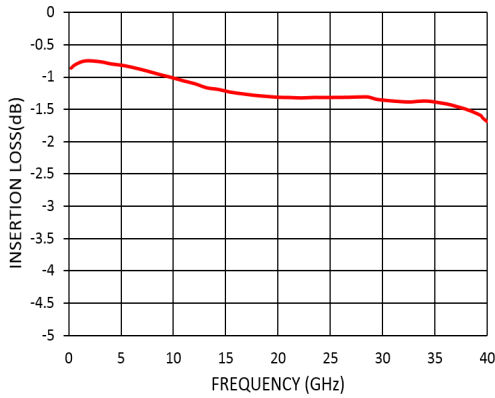
Electrical Specifications

TA = +25°C, VCTL=+5/-5V , ±10 mA Typical

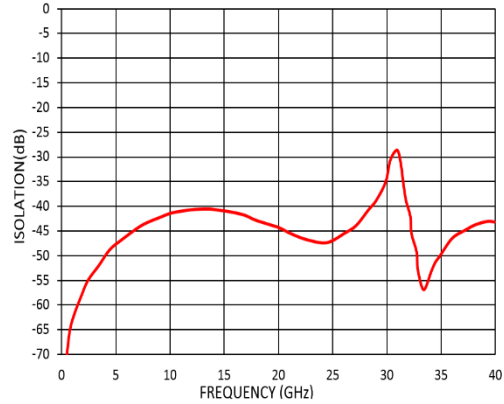
Parameters	Min.	Typ.	Max.	Units
Frequency	0.1		26.5	GHz
Insertion Loss		1.3	1.5	dB
Isolation	35	40		dB
Input Return Loss (ON State)		12		dB
Output Return Loss (OFF State)		16		dB
P1dB - Output 1dB Compression		24		dBm
IIP3-Input Third Order Intercept		40		dBm
Switching Speed		10		ns



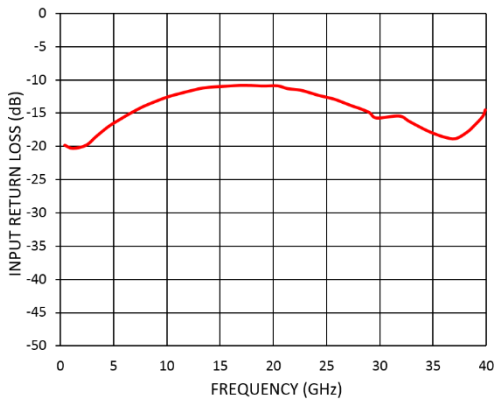
Insertion Loss vs. Frequency



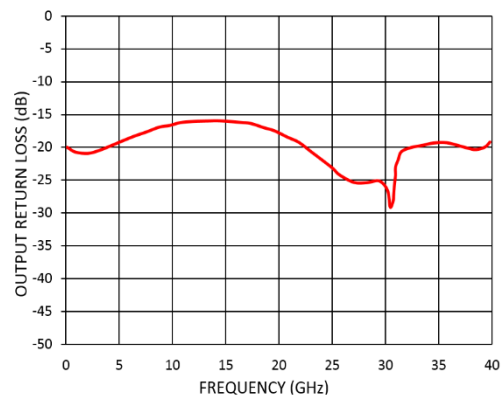
Isolation vs. Frequency



Input Return Loss vs. Frequency



Output Return Loss vs. Frequency





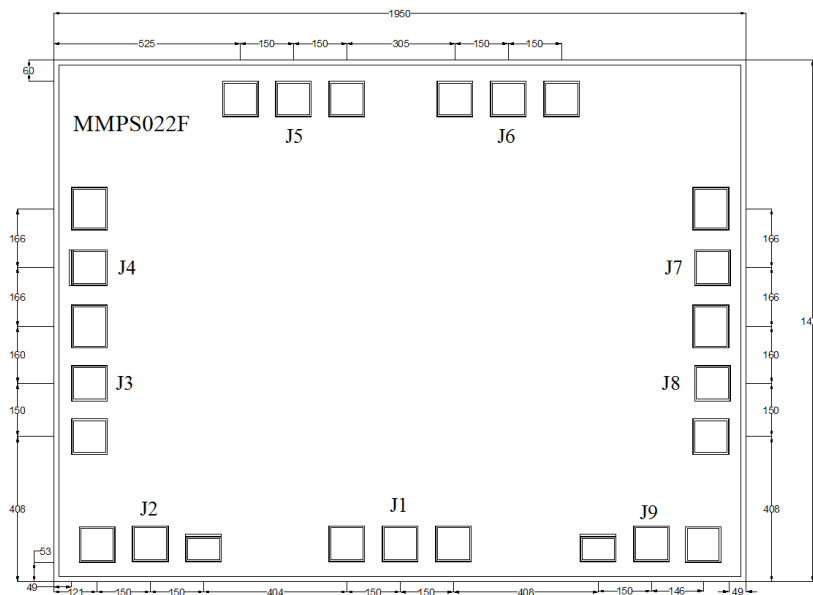
Absolute Maximum Ratings

Max Incident C.W. RF Power	+31dBm
DC Reverse Voltage	25V
Bias Current	±50 mA
Operating Temperature	-55°C to +85 °C
Storage Temperature	-65°C to +150 °C



ELECTROSTATIC SENSITIVE DEVICE
OBSERVE HANDLING PRECAUTIONS

Outline Drawing: All Dimensions in μm

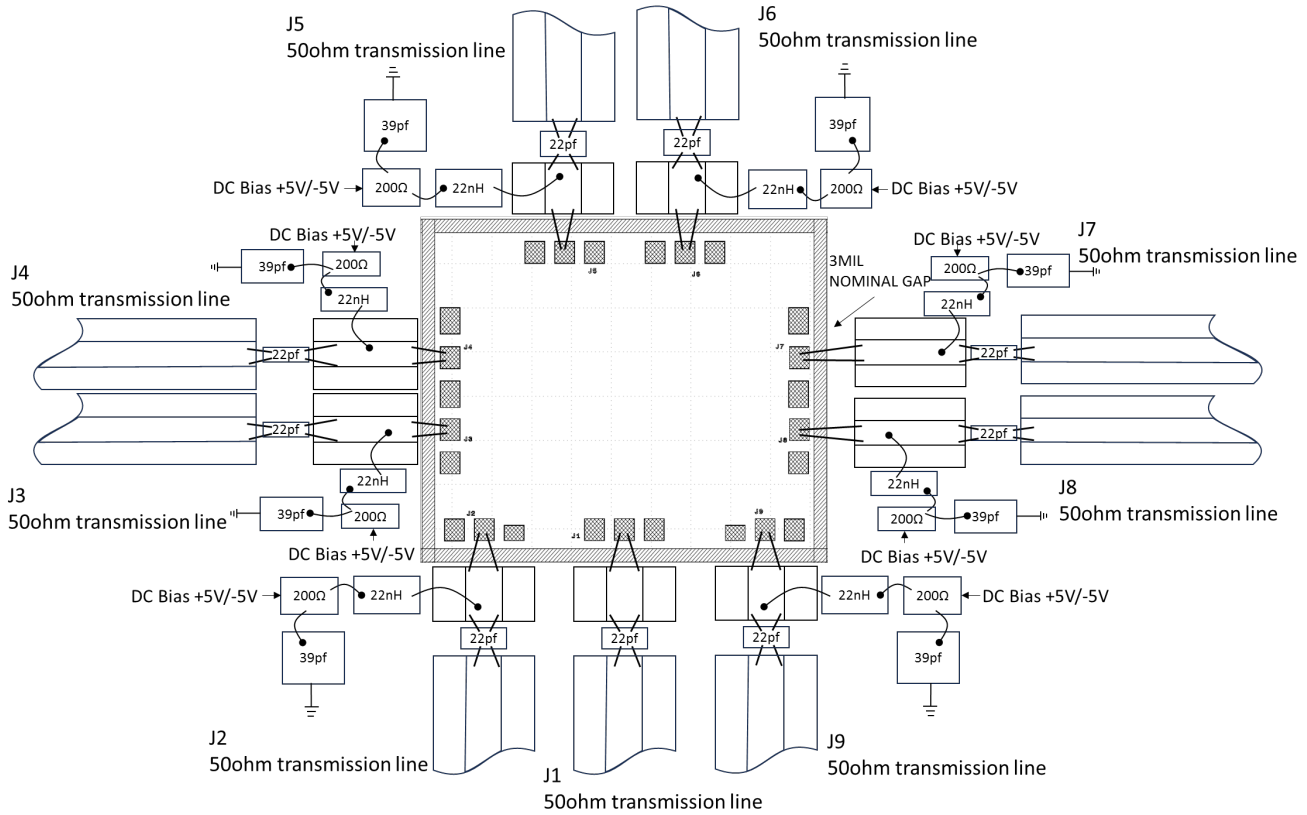


True Table

Control Voltage								State							
J2	J3	J4	J5	J6	J7	J8	J9	J2→J1	J3→J1	J4→J1	J5→J1	J6→J1	J7→J1	J8→J1	J9→J1
-5V	+5V	+5V	+5V	+5V	+5V	+5V	+5V	ON	OFF	OFF	OFF	OFF	OFF	OFF	OFF
+5V	-5V	+5V	+5V	+5V	+5V	+5V	+5V	OFF	ON	OFF	OFF	OFF	OFF	OFF	OFF
+5V	+5V	-5V	+5V	+5V	+5V	+5V	+5V	OFF	OFF	ON	OFF	OFF	OFF	OFF	OFF
+5V	+5V	+5V	-5V	+5V	+5V	+5V	+5V	OFF	OFF	OFF	ON	OFF	OFF	OFF	OFF
+5V	+5V	+5V	+5V	-5V	+5V	+5V	+5V	OFF	OFF	OFF	OFF	ON	OFF	OFF	OFF
+5V	+5V	+5V	+5V	+5V	-5V	+5V	+5V	OFF	OFF	OFF	OFF	OFF	ON	OFF	OFF
+5V	+5V	+5V	+5V	+5V	+5V	-5V	+5V	OFF	OFF	OFF	OFF	OFF	OFF	ON	OFF
+5V	+5V	+5V	+5V	+5V	+5V	+5V	-5V	OFF	OFF	OFF	OFF	OFF	OFF	OFF	ON



Assembly Drawing



Notes:

1. Die thickness: 100µm
2. Typical bond pad is 100*100µm²
3. Bond pad metalization: Gold
4. Backside metallization: Gold
5. Backside of the die (GND)
6. No connection required for unlabeled bond pads

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